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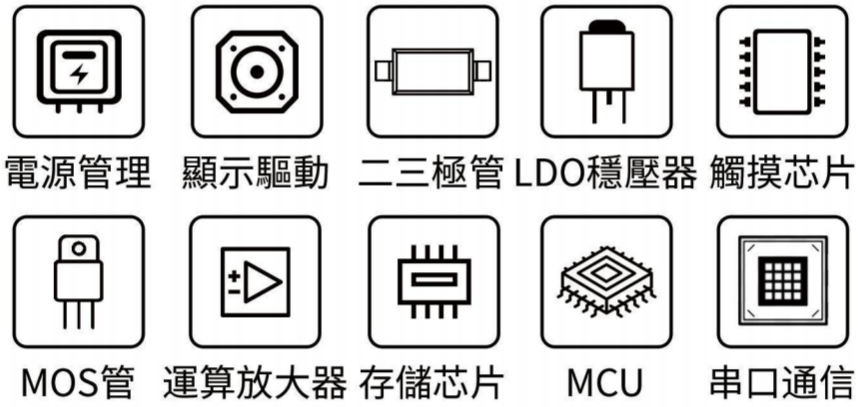


LMV321S-TD

產品規格說明書

TD321, TD358, TD324

1MHz, 40uA, Single/Dual/Quad Rail-to-Rail Input and Output CMOS Operational Amplifier

Features

- Rail-to-Rail Input and Output
- Unit Gain Stable
- Supply Voltage Range: 2.5V to 5.5V
- Thermal Shutdown Protection Circuitry
- Low Input Offset Voltage
  - 0.8mV typical
- Gain Bandwidth Product: 1MHz
- Slew Rate: 5V/us
- Micro Power
  - 40uA/Amplifier Typical Supply Current
- Small Packaging:
  - Available in Green SOT/SOP/DFN Package

Applications

- Wearable Products
- Temperature Measurement
- Battery Powered system
- Sensors

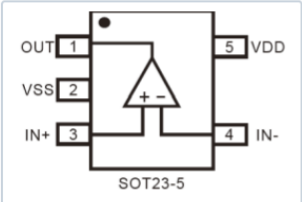
Descriptions

The TD321、TD358、TD324 families of products are rail-to-rail input and output operational amplifier offering low cost and high performance. They have a wide input common-mode voltage range and output voltage swing, running at single supply voltage from 2.5V to 5.5V.

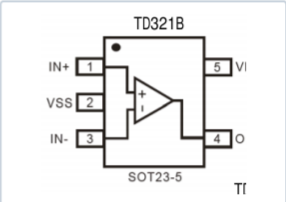
The op-amps provide 1MHz bandwith at a low current consumption of 40uA per amplifier, offering excellent overall performance. The op-amps exhibit low noise and distortion, low offset and high output current capability, making this device an excellent choice for high quality, low voltage or battery operated systems.

The TD321、TD358、TD324 families of products are offered in Green SOT/SOP/DFN packages ,and are specified over the extended -40℃to +125℃ temperature range.

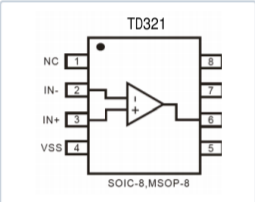
Pin Configurations



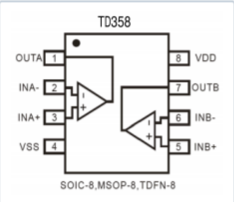
TD321 SOT23-5



TD321B SOT23-5



TD321 SOIC-8



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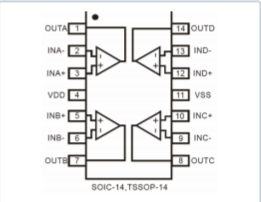
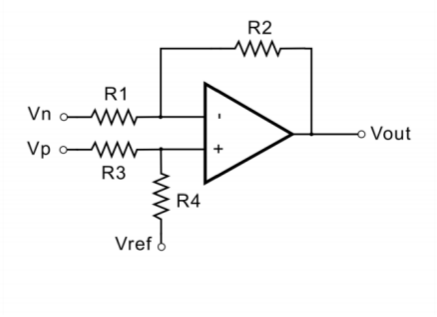
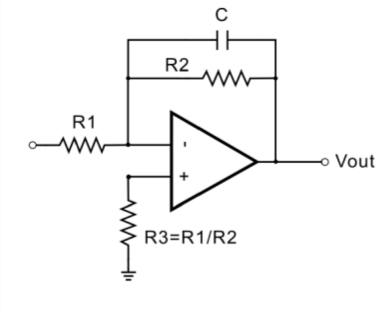


TD324 SOIC-14

Typical Application Circuit



Difference Amplifier



Low Pass Active Filter

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Supply Voltage, $+V_S$ to $-V_S$	6	V
Power Dissipation, P_D @ T_A = 25°C,		W
Package Thermal Resistance (θ_{Jc})		°C/W
Lead Temperature (Soldering, 10 sec.)	260	°C
ESD HBM (Human Body Mode)	8	KV
Operating Temperature Range...	-40 to 125	V

The Recommended Operating Conditions table defines the conditions for actual device operation to ensure optimal performance to the datasheet specifications. T D S E M I C does not recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter	Min.	Typ.	Max.	Unit
Supply Input Voltage		1.4	5.5	V
Junction Temperature Range		-40	125	V
Ambient Temperature Range		-40	85	°C

Electrical Characteristics: V_S = +5V

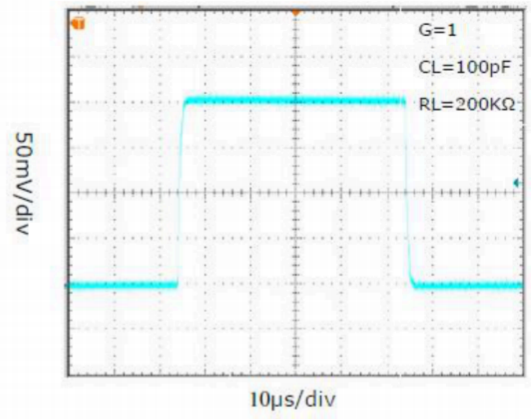
(At V_S = 5V, T_A = +25℃, R_L = 200kΩ connected to V_S/2, unless otherwise noted)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
DYNAMIC PERFORMANCE					
Gain-Bandwidth Product (GBP)	R_L = 100kΩ		1		MHz
Slew Rate	2Vpp Step, A_V = 1		5.0		V/us
Crosstalk	f = 100Hz		120		dB
DC PERFORMANCE					
Input Offset Voltage (V_{OS})		-2.5	0.8	2.5	mV
Input Offset Voltage Drift	V_{CM} = 2.5V		5		uV/deg
Large Signal Voltage Gain (A_{VO})	R_L = 200kΩ, V_{OUT} = 0.15V to 4.85V		120		dB
INPUT CHARACTERISTICS					
Input Common Mode Voltage Range (V_{CM})	V_{CM} = -0.1V to V_{CC} +0.1V	-0.1		5.6	V
Common Mode Rejection Ratio (CMRR)	V_{CM} = -0.1V to V_{CC}+0.1V		85		dB
Input Bias Current (I_B)			1		pA
OUTPUT CHARACTERISTICS					
Output Voltage Swing from Rail	R_L=100K		0.01		V
	R_L=10K		0.1		V
POWER SUPPLY					
Operating Voltage Range		2.25		5.5	V
Quiescent Current (per Amplifier)	I_{OUT} = 0mA		40		uA
Power Supply Rejection Ratio (PSRR)	V_S = +2.1V to + 5.5V, V_{CM} = (-V_S) + 0.5V		75		dB
NOISE/DISTORTION PERFORMANCE					
Integrate Input Voltage Noise	f = 0.1 Hz to 10 Hz		4		uV/pp
Voltage Noise Density (e_n)	f=1kHz		50		nV/rtHz

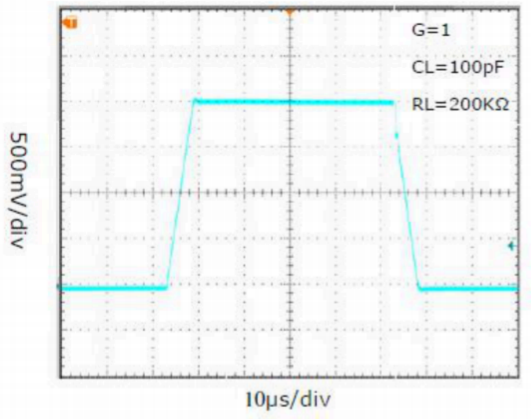
Note 1: Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Typical Performance Characteristics

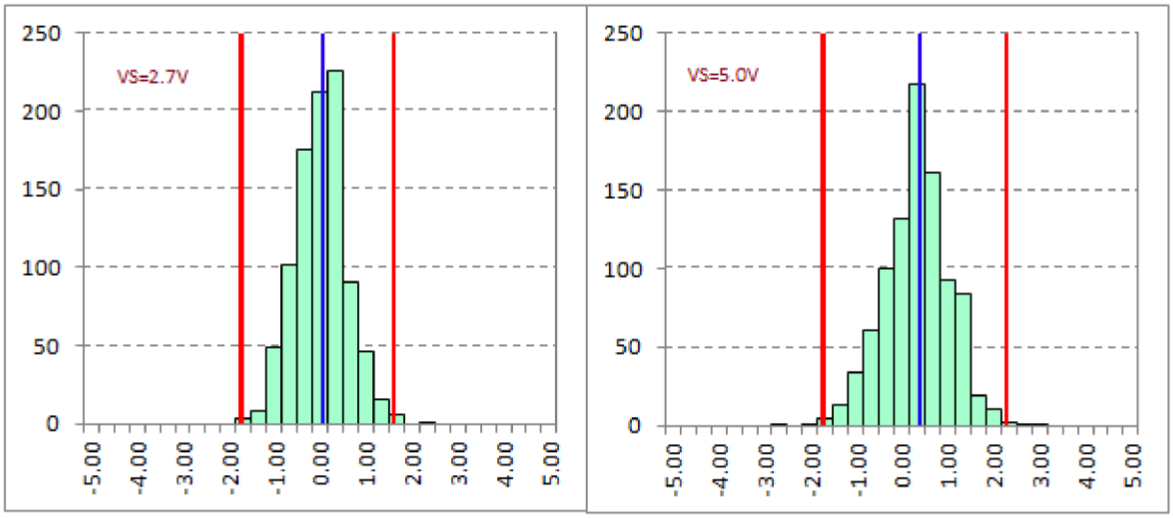
At T_A = +25℃, A_V = +1, C_L = 100pF and R_L = 200kΩ, unless otherwise noted.



Small-Signal Step Response

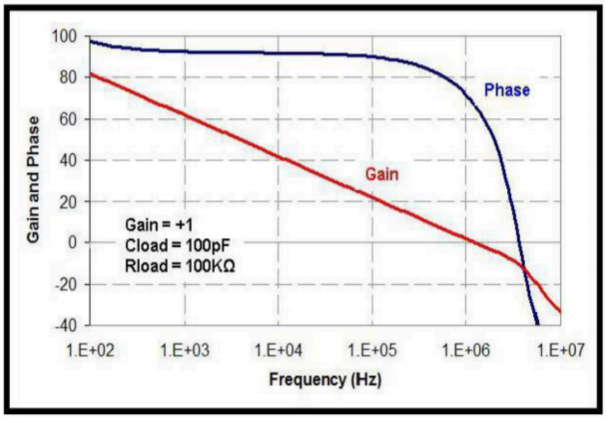


Large-Signal Step Response

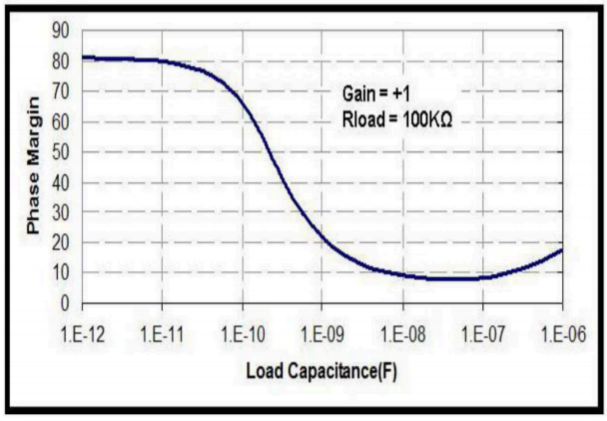


Offset Voltage Distribution (1000 samples, X-axis: mV ; Y-axis: hits) VS=2.1V and VS=5.0V

Open-Loop Gain and Phase

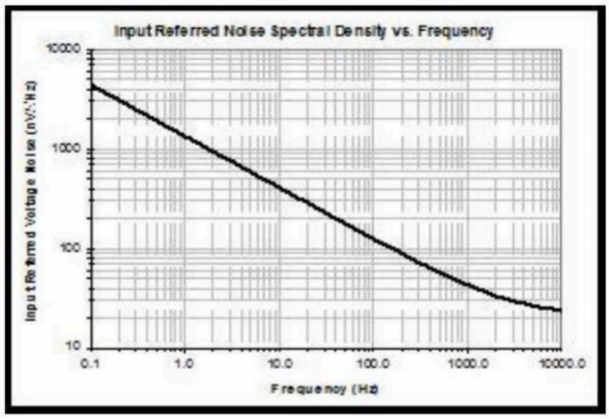


Phase Margin vs. C_{LOAD} (Stable for Any C_{LOAD})

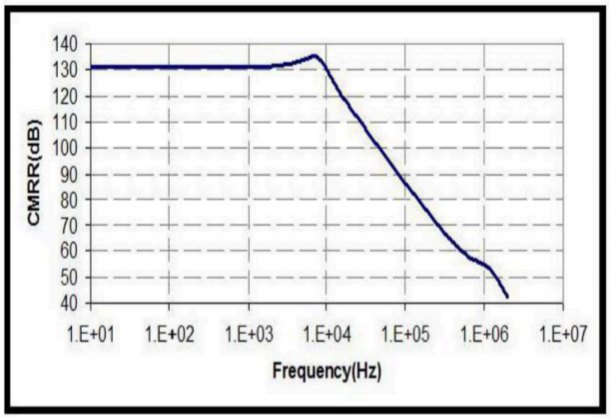


Typical Performance Characteristics (cont.)

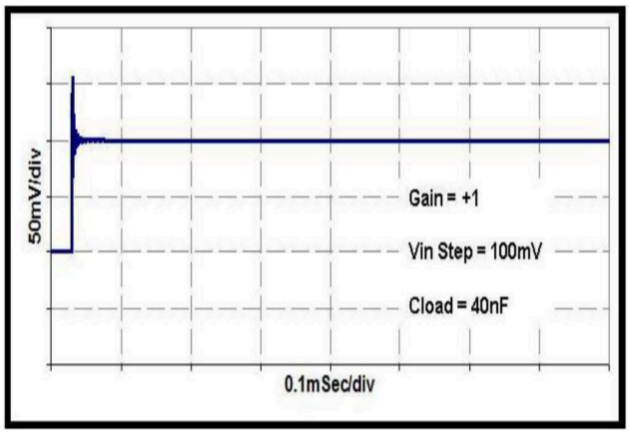
Input Voltage Noise Spectral Density



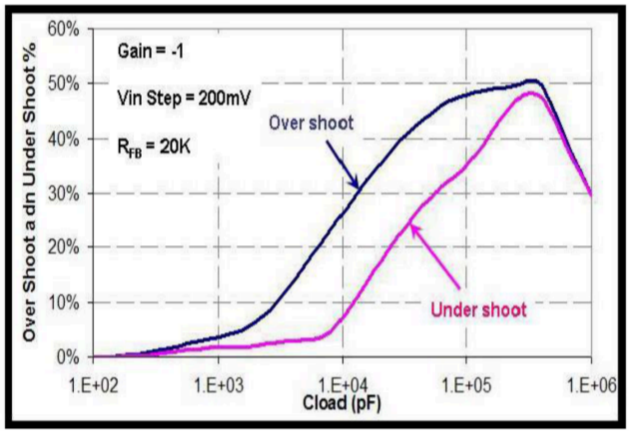
Common-Mode Rejection Ratio



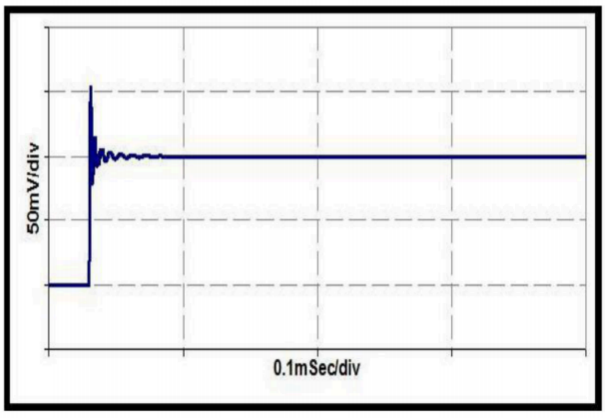
Over-Shoot Voltage, C_{LOAD} = 40nF, Gain = +1



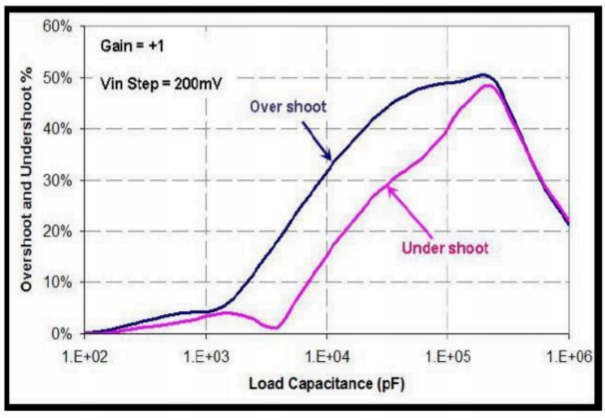
Over-Shoot % vs. C_{LOAD}, Gain = -1, RFB = 20kΩ



Over-Shoot Voltage, C_{LOAD}=40nF, Gain= -1, RFB=100kΩ

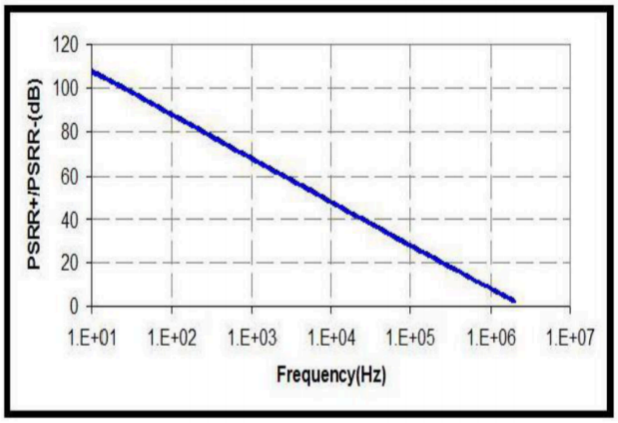


Small-Signal Over-Shoot % vs. C_{LOAD}, Gain = +1

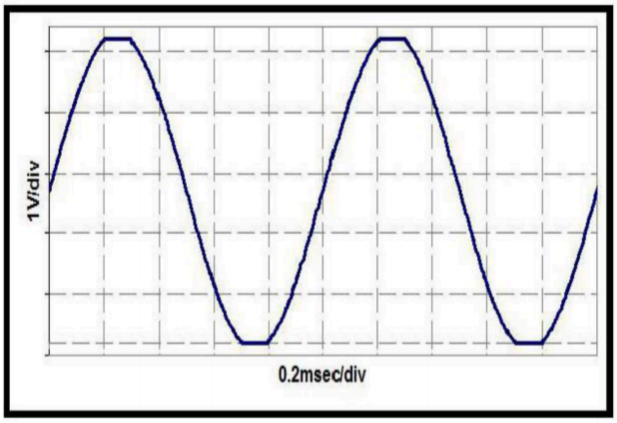


Typical Performance Characteristics (cont.)

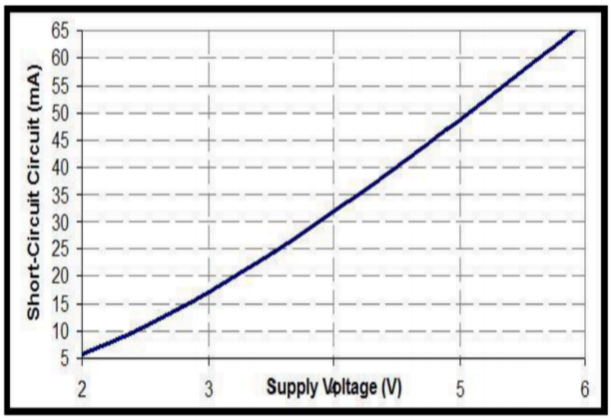
Power-Supply Rejection Ratio



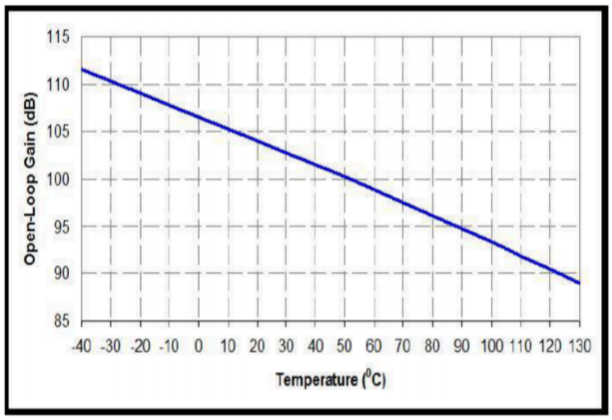
V_{IN} = -0.2V to 5.7V, No Phase Reversal



Short-Circuit Current vs. Supply Voltage



Open-Loop Gain vs. Temperature



Power Supply Layout and Bypass

The TD321、TD358、TD324 OPA's power supply pin (V_{DD} for single-supply) should have a local bypass capacitor (i.e., 0.01μF to 0.1μF) within 2mm for good high frequency performance. It can also use a bulk capacitor (i.e., 1μF or larger) within 100mm to provide large, slow currents. This bulk capacitor can be shared with other analog parts.

Ground layout improves performance by decreasing the amount of stray capacitance and noise at the OPA's inputs and outputs. To decrease stray capacitance, minimize PC board lengths and resistor leads, and place external components as close to the op amps' pins as possible.

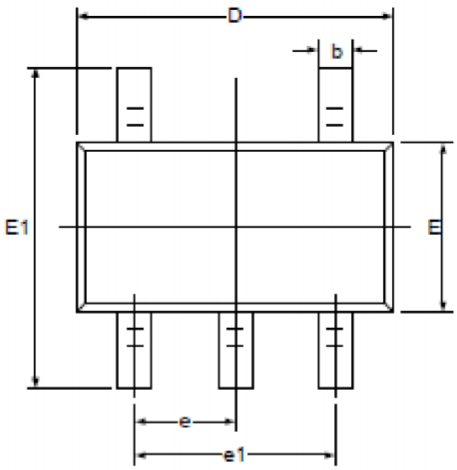
Proper Board Layout

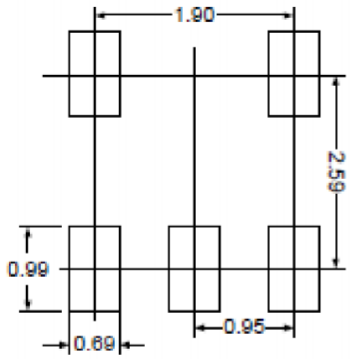
To ensure optimum performance at the PCB level, care must be taken in the design of the board layout. To avoid leakage currents, the surface of the board should be kept clean and free of moisture. Coating the surface creates a barrier to moisture accumulation and helps reduce parasitic resistance on the board. Keeping supply traces short and properly bypassing the power supplies minimizes power supply disturbances due to output current variation, such as when driving an ac signal into a heavy load. Bypass capacitors should be connected as closely as possible to the device supply pins. Stray capacitances are a concern at the outputs and the inputs of the amplifier. It is recommended that signal traces be kept at least 5mm from supply lines to minimize coupling.

A variation in temperature across the PCB can cause a mismatch in the Seebeck voltages at solder joints and other points where dissimilar metals are in contact, resulting in thermal voltage errors. To minimize these thermocouple effects, orient resistors so heat sources warm both ends equally. Input signal paths should contain matching numbers and types of components, where possible to match the number and type of thermocouple junctions. For example, dummy components such as zero value resistors can be used to match real resistors in the opposite input path. Matching components should be located in close proximity and should be oriented in the same manner. Ensure leads are of equal length so that thermal conduction is in equilibrium. Keep heat sources on the PCB as far away from amplifier input circuitry as is practical.

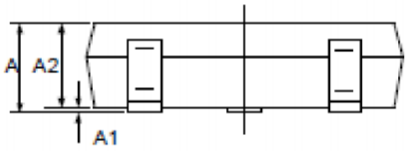
The use of a ground plane is highly recommended. A ground plane reduces EMI noise and also helps to maintain a constant temperature across the circuit board.

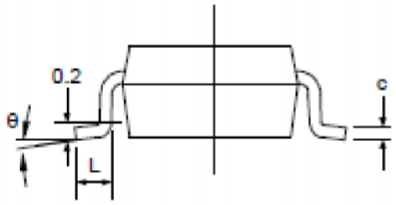
Package Outline And Physical Dimensions: SOT23-5





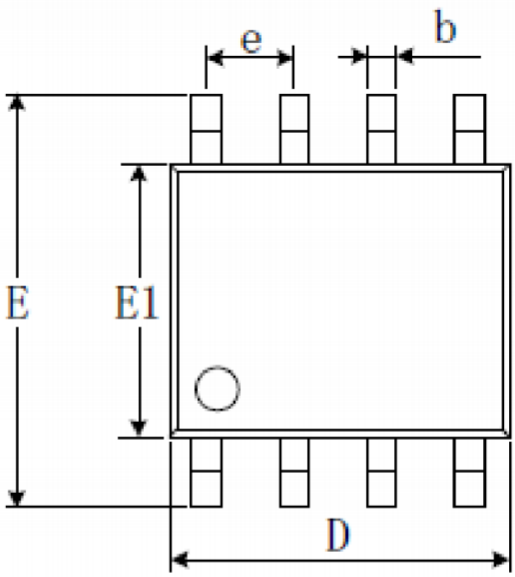
RECOMMENDED LAND PATTERN (Unit: mm)

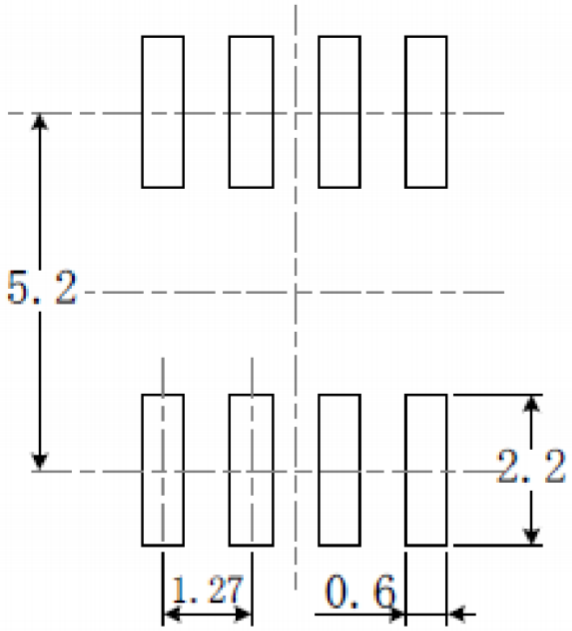




Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Package Outline And Physical Dimensions: SOIC-8





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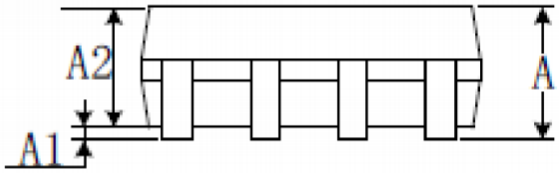
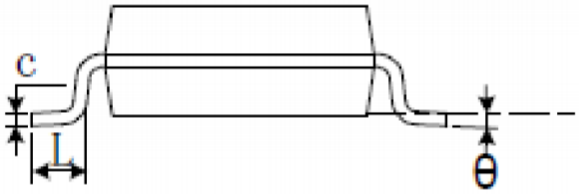
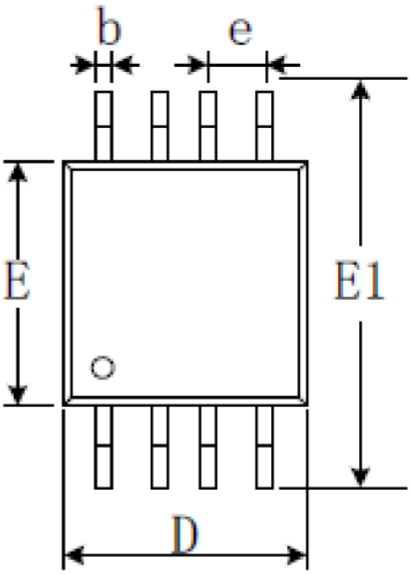
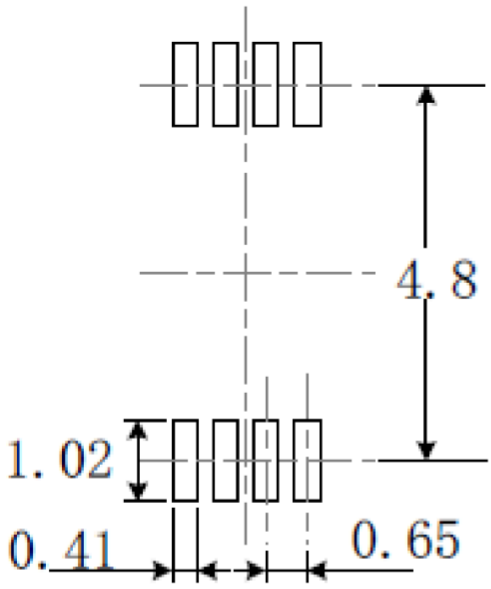




Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Package Outline And Physical Dimensions: MSOP-8





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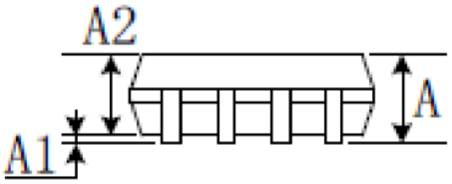
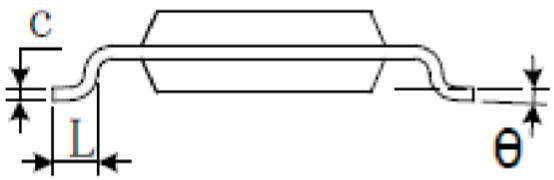
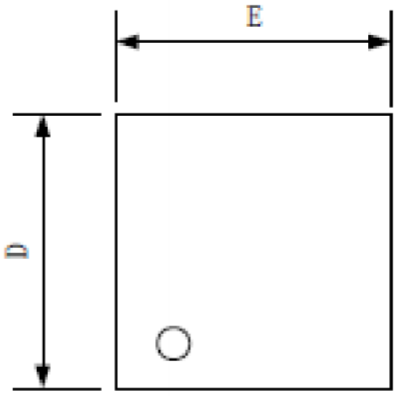


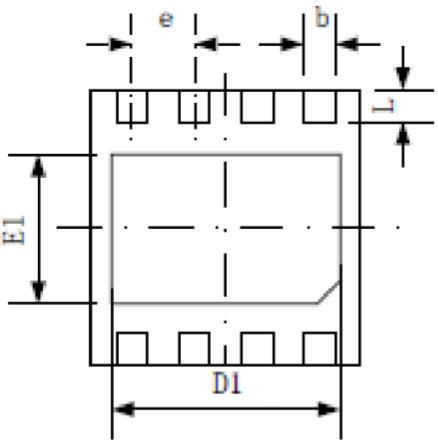


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
e	0.650(BSC)		0.026(BSC)	
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

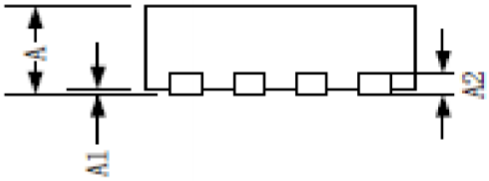
Package Outline And Physical Dimensions: TDFN-8



TOP VIEW



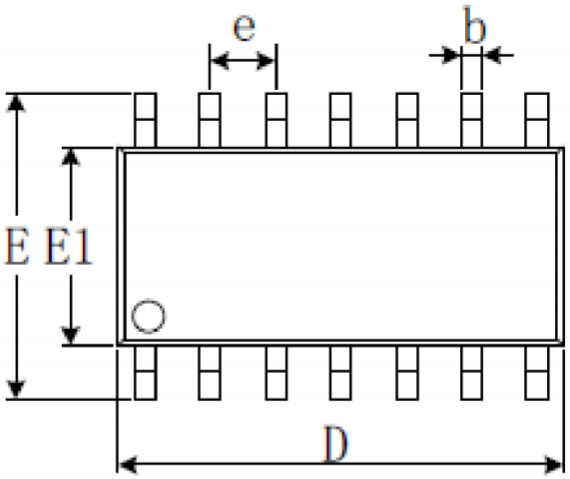
BOTTOM VIEW

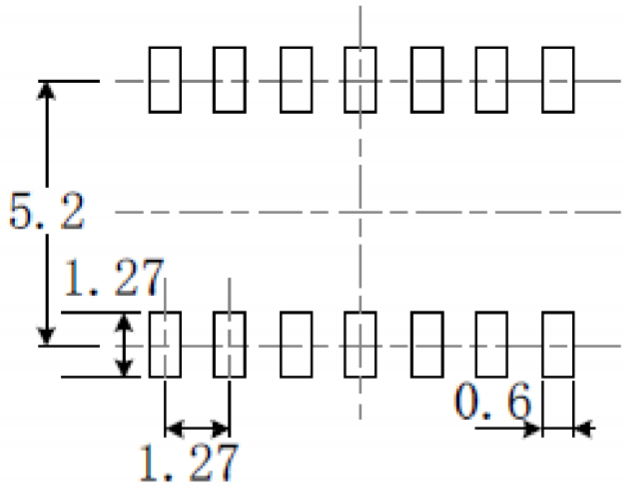


SIDE VIEW

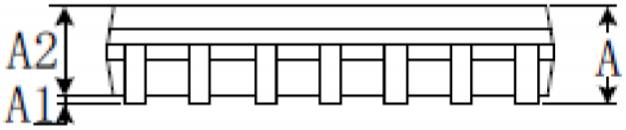
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203		0.008	
b	0.300	0.400	0.012	0.016
D	2.900	3.100	0.114	0.122
D1	2.510	2.610	0.099	0.103
E	2.900	3.100	0.114	0.122
E1	1.550	1.650	0.061	0.065
e	0.650 TYP		0.026 TYP	
L	0.350	0.450	0.014	0.018

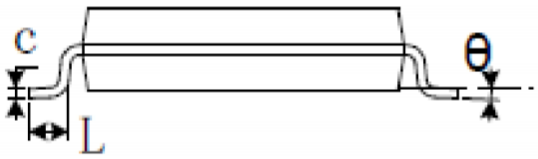
Package Outline And Physical Dimensions: SOP-14





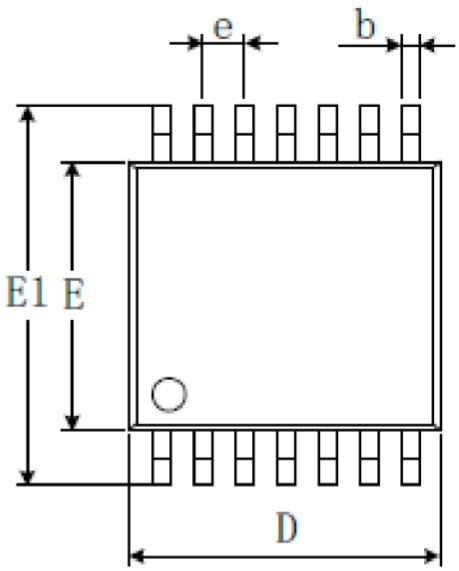
RECOMMENDED LAND PATTERN (Unit: mm)

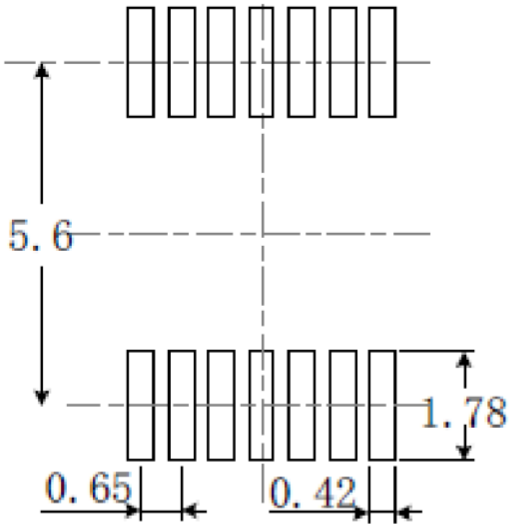




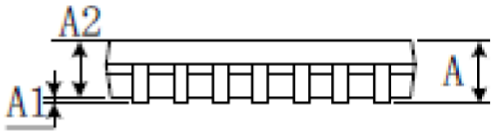
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D	8.450	8.850	0.333	0.348
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

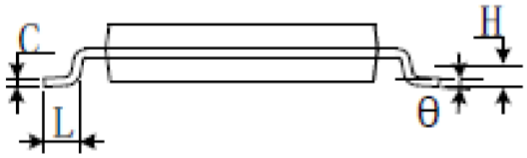
Package Outline And Physical Dimensions: TSSOP-14





RECOMMENDED LAND PATTERN (Unit: mm)





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	4.860	5.100	0.191	0.201
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC)		0.026(BSC)	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°